

# **DATA SHEET**

Product Name High Resistance Thick Film Chip Resistors

Part Name 0603/0805/1206/1210 Series File No. SMD-SP-002

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#### 1. <u>Scope</u>

- 1.1 This datasheet is the characteristics of High Resistance Thick Film Chip Resistors manufactured by UNI-ROYAL.
- 1.2 High Resistance.
- 1.3 Suitable for reflow & wave soldering.
- 1.4 Application AV adapters , LCD back-light camera strobe etc.

# 2. Part No. System

- Part No. includes 14 codes shown as below:
- 2.1 1<sup>st</sup>~4<sup>th</sup> codes: Part name. E.g.: 0603, 0805, 1206 ,1210.

 $2.25^{\text{th}} \sim 6^{\text{th}}$  codes: Power rating.

E.g.: W=N	Normal Size	"1~G	" = "1~16"		
	Wattage	1/2	1/4	1/8	1/10
	Normal Size	W2	W4	W8	WA

If power rating is equal or lower than 1 watt,  $5^{th}$  code would be "W" and  $6^{th}$  code would be a number or letter. E.g.: WA=1/10W W4=1/4W

2.3  $7^{\text{th}}$  code: Tolerance. E.g.: D=±0.5% F=±1% G=±2% J=±5% K=±10%

#### 2.4 8<sup>th</sup>~11<sup>th</sup> codes: Resistance value.

- 2.4.1 If value belongs to standard value of E-24 series, the  $8^{th}$  code is zero,  $9^{th} \sim 10^{th}$  codes are the significant figures of resistance value, and the  $11^{th}$  code is the power of ten.
- 2.4.2 If value belongs to standard value of E-96 series, the  $8^{th} \sim 10^{th}$  codes are the significant figures of resistance value, and the  $11^{th}$  code is the power of ten.

#### 2.4.3 11<sup>th</sup> codes listed as following:

 $0=10^{0} \quad 1=10^{1} \qquad 2=10^{2} \quad 3=10^{3} \quad 4=10^{4} \quad 5=10^{5} \quad 6=10^{6} \quad J=10^{-1} \quad K=10^{-2} \quad L=10^{-3} \quad M=10^{-4} \quad L=10^{-3} \quad M=10^{-4} \quad L=10^{-4} \quad$ 

### $2.5 \ 12^{th} \sim 14^{th}$ codes.

 $2.5.1 \ 12^{th} \ code: Packaging \ Type. \ E.g.: \ B = Bulk \ / \ Box \qquad T=Tape/Reel$ 

#### 2.5.2 13th code: Standard Packing Quantity.

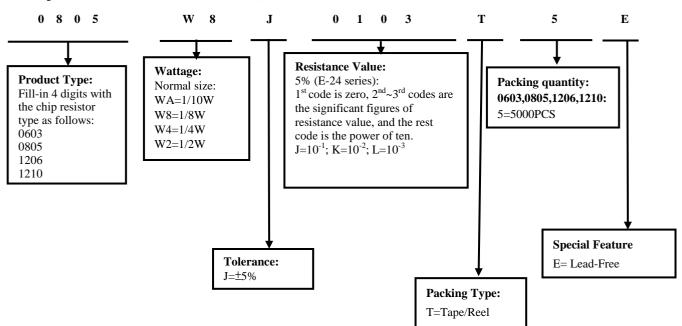
4=4,000pcs 5=5,000pcs C=10,000pcs D=20,000pcs E=15,000pcs Chip Product: BD=B/B-20000pcs TC=T/R-10000pcs

2.5.3 14<sup>th</sup> code: Special features.

E = Environmental Protection, Lead Free, or Standard type.

# 3. Ordering Procedure:

#### (Example: 0805 1/8W ±5% 10KΩ T/R-5000)







#### 4. Marking

 $4.1\pm5\%$  tolerance products (E-24 series): 3 codes.

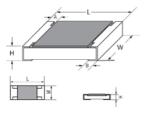
 $1^{st} \sim 2^{nd}$  codes are the significant figures of resistance value, and the rest code is the power of ten.



 $104 \rightarrow 100 \text{K}\Omega$ 

# 5. Dimension

T		Di	mension(mm)		
Туре	L W		н	Α	В
0603	1.60±0.10	0.80±0.10	0.45±0.10	0.30±0.20	0.30±0.20
0805	2.00±0.15	1.25+0.15/-0.10	0.55±0.10	0.40±0.20	0.40±0.20
1206	3.10±0.15	1.55 +0.15/-0.10	0.55±0.10	0.45±0.20	0.45±0.20
1210	3.10±0.10	2.60±0.20	0.55±0.10	0.50±0.25	0.50±0.20



#### 6. Ratings

Туре	Power Rating	Max. Working Voltage	Max. Overload Voltage	Dielectric withstanding Voltage	Operating Temperature	Resistance Range 5%
0603	1/10W	75V	150V	300V	-55℃~155℃	10M~100M
0805	1/8W	150V	300V	500V	-55℃~155℃	10M~100M
1206	1/4W	200V	400V	500V	-55℃~155℃	10M~100M
1210	1/2W	200V	500V	500V	-55℃~155℃	10M~100M

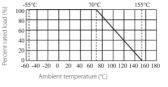
#### 7. Soldering pad size recommended

· · · · · · · · · · · · · · · · · · ·	<b>T</b>		Dimen	sion(mm)	
	Туре	Α	В	С	D
	0603	0.9±0.05	0.65±0.05	$0.8 \pm 0.05$	2.1±0.05
←B→←A→	0805	1.0±0.1	1.0±0.1	1.3±0.1	3.0±0.1
←D→	1206	2.0±0.1	1.1±0.1	1.6±0.1	4.2±0.1
Product	1210	2.0±0.1	1.1±0.1	2.6±0.1	4.2±0.1
Welding plate					

# 8. Derating Curve

Power rating will change based on continuous load at ambient temperature from -55 to 155 °C. It is constant between -55 to 70 °C, and derate to zero when temperature rise from 70 to 155 °C. Voltage rating:

Resistors shall have a rated direct-current (DC) continuous working voltage or an approximate sine-wave root-mean-square (RMS) alternating-current (AC) continuous working voltage at commercial-line frequency and waveform corresponding to the power rating, as determined from the following formula:



 $RCWV = \sqrt{P \times R}$ 

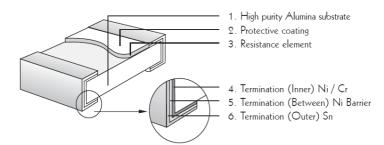
Remark: RCWV: Rating Continuous Working Voltage (Volt.) P: power rating (Watt) R: nominal resistance ( $\Omega$ ) In no case shall the rated DC or RMS AC continuous working voltage be greater than the applicable maximum value. The overload voltage is 2.5 times RCWV or Max. Overload voltage whichever is lower.



High Resistance Thick Film Chip Resistors



# 9. <u>Structure</u>



# 10. <u>Performance Specification</u>

Characteristic	Limits	Test Methods (GB/T 5729&JIS-C-5201&IEC60115-1)
Temperature Coefficient	±200PPM/°C	4.8 Natural resistance changes per temp. Degree centigrade $\frac{R_2 \cdot R_1}{R_1(t_2 \cdot t_1)} \times 10^6 (\text{PPM/°C})$ R <sub>1</sub> : Resistance Value at room temperature (t <sub>1</sub> ); R <sub>2</sub> : Resistance at test temperature (t <sub>2</sub> ) t <sub>1</sub> : +25°C or specified room temperature t <sub>2</sub> : Test temperature (-55°C or 125°C)
Short-time overload	±(2.0%+0.05Ω)	4.13 Permanent resistance change after the application of a potential of 2.5 times RCWV or Max. Overload Voltage whichever less for 5 seconds
Dielectric withstanding voltage	No evidence of flashover mechanical damage, arcing or insulation breaks down.	4.7 Resistors shall be clamped in the trough of a 90°C metallic v- block and shall be tested at ac potential respectively specified in the given list of each product type for 60-70 seconds.
Solderability	Coverage must be over 95%.	4.17 The area covered with a new, smooth, clean, shiny and continuous surface free from concentrated pinholes. Temperature of solder:245±3°C; Dwell time in solder: 2~3 seconds.
Rapid change of temperature	±(1.0%+0.05Ω)	4.19 30 min at -55 °C and 30 min at 155°C; 100 cycles.
Soldering heat	±(1.0%+0.05Ω)	4.18 Dip the resistor into a solder bath having a temperature of $260^{\circ}C\pm5^{\circ}C$ and hold it for $10\pm1$ seconds.
Terminal bending	±(1.0%+0.05Ω)	4.33 Twist of test board: Y/X = 3/90 mm for 60Seconds
Insulation resistance	≥1,000 MΩ	4.6 The measuring voltage shall be ,measured with a direct voltage of $(100 \pm 15)$ V or a voltage equal to the dielectric withstanding voltage., and apply for 1min.
Humidity ( steady state )	±(3.0%+0.05Ω)	4.24Temporary resistance change after 240 hours exposure in a humidity test chamber controlled at $40\pm2$ °C and 90-95% relative humidity,
Load life in humidity	±(3.0%+0.05Ω)	7.9 Resistance change after 1,000 hours (1.5 hours "ON",0.5 hour "OFF") at RCWV in a humidity chamber controlled at 40 $^{\circ}C \pm 2^{\circ}C$ and 90 to 95% relative humidity.
Load life	±(3.0%+0.05Ω)	4.25.1 Permanent resistance change after 1,000 hours operating at RCWV with duty cycle 1.5 hours "ON", 0.5 hour "OFF" at 70 $^{\circ}C \pm 2^{\circ}C$ ambient.
Low Temperature Storage	±(3.0%+0.05Ω)	IEC 60068-2-1 (Aa) Lower limit temperature , for 2H.
High Temperature Exposure	±(3.0%+0.05Ω)	MIL-STD-202 108A Upper limit temperature , for 1000H.
Leaching	No visible damage	J-STD-002 Test D Samples completely immersed for 30 sec in solder bath at 260°C

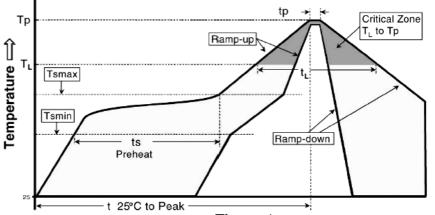




# 11. Soldering Condition

#### (This is for recommendation, please customer perform adjustment according to actual application)

11.1 Recommend Reflow Soldering Profile : (solder : Sn96.5 / Ag3 / Cu0.5)



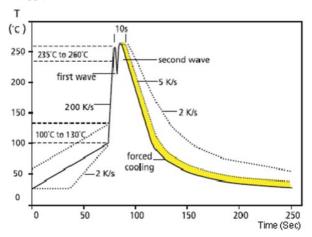
Time 📥

Profile Feature	Lead (Pb)-Free solder
Preheat:	
Temperature Min (Ts <sub>min</sub> )	150°C
Temperature Max (Ts <sub>max</sub> )	200°C
Time $(Ts_{min} \text{ to } Ts_{max})$ (ts)	60 -120seconds
Average ramp-up rate:	
(Ts max to Tp)	$3^{\circ}$ C / second max.
Time maintained above :	
Temperature (T <sub>L</sub> )	217°C
Time $(t_L)$	60-150 seconds
Peak Temperature (Tp)	260°C
Time within $^{+0}_{-5}$ °C of actual peak Temperature (tp) <sup>2</sup>	10 seconds
Ramp-down Rate	6°℃/second max.
Time $25^{\circ}$ C to Peak Temperature	8minutes max.

Allowed Re-flow times : 2 times

Remark : To avoid discoloration phenomena of chip on terminal electrodes, please use N2 Re-flow furnace .

11.2 Recommend Wave Soldering Profile : (Apply to 0603 and above size)



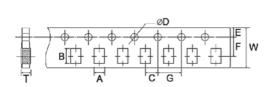




# 12. <u>Packing</u>

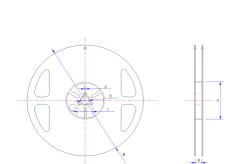
12.1 Dimension of Paper Taping :(Unit: mm)

Туре	A ±0.2	B ±0.2	C ±0.05	$\Phi D^{+0.1}_{-0}$	E ±0.1	F ±0.05	G ±0.1	W ±0.2	T ±0.1
0603	1.10	1.90	2.00	1.50	1.75	3.50	4.00	8.00	0.67
0603	1.10	1.90	2.00	1.50	1.75	5.50	4.00	8.00	0.67
0805	1.65	2.40	2.00	1.50	1.75	3.50	4.00	8.00	0.81
1206	2.00	3.60	2.00	1.50	1.75	3.50	4.00	8.00	0.81
1210	2.80	3.50	2.00	1.50	1.75	3.50	4.00	8.00	0.75



#### 12.2 Dimension of plastic taping : (Unit: mm)

Туре	Taping	Qty/Reel	A ±0.5	В ±0.5	C ±0.5	D ±1	M ±2	W ±1
0603	Paper	5,000pcs	2.0	13.0	21.0	60.0	178.0	10.0
0805	Paper	5,000pcs	2.0	13.0	21.0	60.0	178.0	10.0
1206	Paper	5,000pcs	2.0	13.0	21.0	60.0	178.0	10.0
1210	Paper	5,000pcs	2.0	13.0	21.0	60.0	178.0	10.0



# 13. <u>Note</u>

13.1 UNI-ROYAL recommend products store in warehouse with temperature between 15 to 35 °C under humidity between 25 to 75% RH. Even under storage conditions recommended above, solder ability of products will be degraded stored over 1 year old.

13.2 Cartons must be placed in correct direction which indicated on carton, otherwise the reel or wire will be deformed.

13.3 Storage conditions as below are inappropriate:

a. Stored in high electrostatic environment

b. Stored in direct sunshine, rain, snow or condensation.

c. Exposed to sea wind or corrosive gases, such as Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, NO<sub>2</sub>, etc.

13.4 The products are used in circuit board thickness greater than 1.6mm. If customers use less than the thickness of the circuit board that you should confirm with the company, in order to recommend a more suitable product.

#### 14. Record

Version	Description	Page	Date	Amended by	Checked by
1	First version	1~6	Mar.20, 2018	Haiyan Chen	Nana Chen
2	Modify characteristic	4~5	Feb.12, 2019	Haiyan Chen	Yuhua Xu
3	Modify the High Temperature Exposure conditions	5	July.29, 2019	Haiyan Chen	Yuhua Xu
4	Modify the reflow curve and add the wave soldering curve	5	Apr.29, 2020	Haiyan Chen	Yuhua Xu
5	Modify the temperature coefficient test conditions	4	Oct.13, 2022	Haiyan Chen	Yuhua Xu

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